### **A02555NUTG Series**

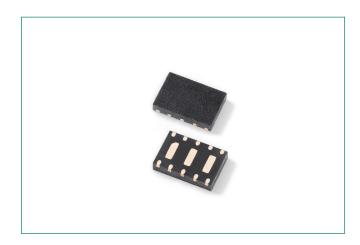
**Lightning Surge Protection** 





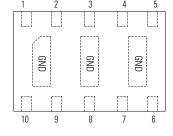






#### **Pinout**

# **Top View**



**Bottom View** 

Note: PIN3, PIN8 are same potential with GND

#### **Description**

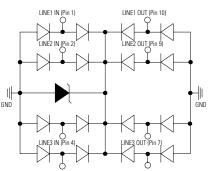
The AQ2555NUTG is a low-capacitance, TVS Diode Array designed to provide protection against ESD (electrostatic discharge), CDE (cable discharge events), EFT (electrical fast transients), and lightning induced surges for high-speed, differential data lines. It's packaged in a  $\mu$ DFN package (3.0 x 2.0mm) and each component can protect up 4 channels or 2 differential pairs, up to 45A (IEC 61000-4-5 2nd edition,) and up to 30kV ESD (IEC 61000-4-2). The "flow-through" design minimizes signal distortion, reduces voltage overshoot, and provides a simplified PCB design.

The AQ2555NUTG with its low capacitance and low clamping voltage makes it ideal for high-speed data interfaces such as 1GbE applications found in notebooks, switches, etc.

#### **Features**

- ESD, IEC 61000-4-2, ±30kV contact, ±30kV air
- •EFT, IEC 61000-4-4, 50A (5/50ns)
- Lightning, IEC 61000-4-5 2nd edition, 45A (tP=8/20us)
- Low capacitance of 2.5pF@0V (TYP) per I/O
- Low leakage current of 0.1µA (TYP) at 2.5V
- PPAP capable
- µDFN-10 package is optimized for high-speed data line routing

- Provides protection for two differential data pairs (4 channels) up to 45A
- Low operating and clamping voltage
- AEC-Q101 qualified
- Halogen free, Lead free and RoHS compliant
- Moisture Sensitivity Level(MSL -1)



- **Functional Block Diagram**
- LINE4 IN (Pin 5)

Life Support Note:

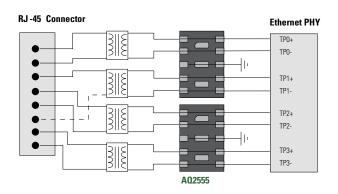
#### Not Intended for Use in Life Support or Life Saving Applications

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

#### **Applications**

- 10/100/1000 Ethernet
- WAN/LAN Equipment
- Desktops, Servers and Notebooks
- LVDS Interfaces
- Integrated Magnetics
- Automotive Application

#### **Application Expample**





# **AQ2555NUTG Series**Lightning Surge Protection

#### **Absolute Maximum Ratings**

Symbol	Parameter	Value	Units
I <sub>PP</sub>	Peak Current (t <sub>n</sub> =8/20µs)	45	А
$P_{Pk}$	Peak Pulse Power (t <sub>p</sub> =8/20µs)	1000	W
T <sub>OP</sub>	Operating Temperature	-40 to 150	°C
T <sub>STOB</sub>	Storage Temperature	-55 to 150	°C

Caution: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the component. This is a stress only rating and operation of the component at these or any other conditions above those indicated in the operational sections of this specification is not implied.

#### Electrical Characteristics (T<sub>OP</sub>=25°C)

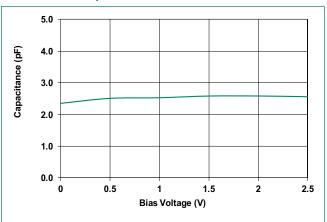
Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Reverse Standoff Voltage	$V_{_{\mathrm{RWM}}}$	$I_R \le 1 \mu A$			2.5	V
Reverse Leakage Current	I <sub>R</sub>	$V_{RWM} = 2.5V, T = 25^{\circ}C$		0.1	0.5	μΑ
Snap Back Voltage	$V_{SB}$	$I_{SB} = 50 \text{mA}$	2.0			V
Clamp Voltage	V <sub>c</sub>	$I_{pp} = 1A$ , $t_p = 8/20\mu s$ , Any I/O to Ground		4.5		V
		$I_{pp} = 10A$ , $t_p = 8/20\mu s$ , Any I/O to Ground		7.5		
		$I_{pp} = 25A$ , $t_p = 8/20\mu s$ , Any I/O to Ground		12		
		$I_{pp} = 45A$ , $t_p = 8/20\mu s$ , Line-to-Line <sup>1</sup> , two I/O Pins connected together on each line		19		
Dynamic Resistance <sup>2</sup>	R <sub>DYN</sub>	TLP, $t_p = 100$ ns, Any I/O to Ground		0.1		Ω
ESD Withstand Voltage	\/	IEC 61000-4-2 (Contact)	±30			kV
	V <sub>ESD</sub>	IEC 61000-4-2 (Air)	±30		kV	
Diode Capacitance	C <sub>I/O to GND</sub>	Between I/O Pins and Ground $V_R = 0V$ , $f = 1MHz$		2.5		pF
	C <sub>I/O to I/O</sub>	Between I/O Pins $V_B = 0V$ , $f = 1MHz$		1.2		pF



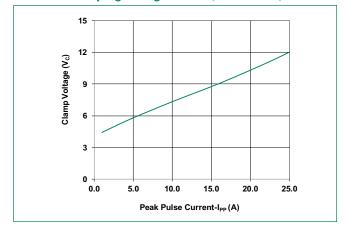
<sup>1.</sup> Rating with 2 pins connected together per sugguested diagram (For example, pin1 is connected to pin 10, pin 2 is connected to Pin 9, Pin 4 is connected to pin 7 and pin 5 is connected to pin 6) 2. Transmission Line Pulse (TLP) with 100ns width, 2ns rise time, and average window t1=70ns to t2=90ns

# **AQ2555NUTG Series**Lightning Surge Protection

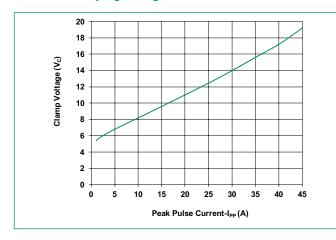
#### Capacitance vs. Reverse Bias



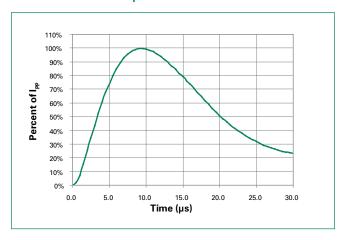
#### Clamping Voltage vs. IPP (I/O to GND)



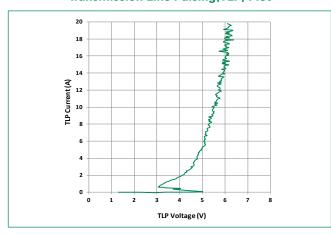
#### Clamping Voltage vs. IPP (Line-to-Line)



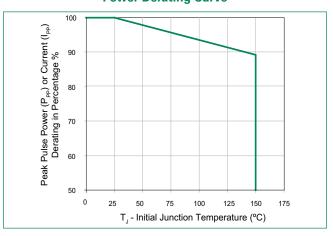
#### 8/20µs Pulse Waveform



#### **Transmission Line Pulsing(TLP) Plot**



#### **Power Derating Curve**



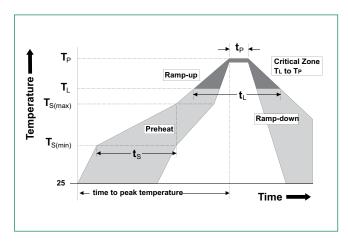


# **AQ2555NUTG Series**

## Lightning Surge Protection

#### **Soldering Parameters**

Reflow Condition		Pb – Free assembly		
Pre Heat	- Temperature Min (T <sub>s(min)</sub> )	150°C		
	- Temperature Max (T <sub>s(max)</sub> )	200°C		
	-Time (min to max) (t <sub>s</sub> )	60 - 120 secs		
Average rar peak	mp up rate (Liquidus) Temp (T <sub>L</sub> ) to	3°C/second max		
T <sub>S(max)</sub> to T <sub>L</sub>	Ramp-up Rate	3°C/second max		
Reflow	- Temperature (T <sub>L</sub> ) (Liquidus)	217°C		
	- Temperature (t <sub>L</sub> )	60 – 150 seconds		
Peak Tempe	rature (T <sub>P</sub> )	260 <sup>+0/-5</sup> °C		
Time within 5°C of actual peak Temperature (tp)		30 seconds		
Ramp-down	n Rate	6°C/second max		
Time 25°C to peak Temperature (T <sub>P</sub> )		8 minutes Max.		
Do not exce	eed	260°C		



#### **Ordering Information**

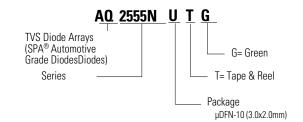
Part Number	Package	Min. Order Qty.
AQ2555NUTG	μDFN-10 (3.0x2.0mm)	3000

#### **Product Characteristics**

Lead Plating	Pre-Plated Frame
Lead Material	Copper Alloy
Substrate material	Silicon
Body Material	Molded Compound
Flammability	UL Recognized compound meeting flammability rating V-0

- Notes:
  1. All dimensions are in millimeters
- Dimensions include solder plating.
   Dimensions are exclusive of mold flash & metal burr.

#### **Part Numbering System**



#### **Part Marking System**



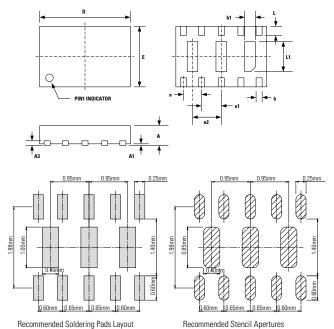
First row= Part Name= AQ2555 Second row= Assembly Code+ Date Code



# **AQ2555NUTG Series**

## Lightning Surge Protection

#### Package Dimensions - µDFN-10 (3.0x2.0mm)

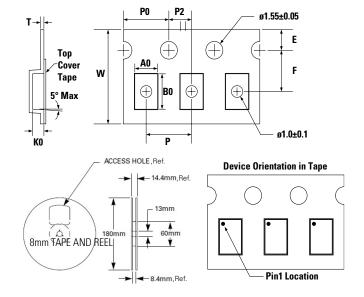


Recommended Stencil thickness 5mils

Package	μDFN-10 (3.0x2.0mm)							
JEDEC		MO-229						
Cumbal	Millimeters			Inches				
Symbol	Min	Nom	Max	Min	Nom	Max		
Α	0.50	0.60	0.65	0.020	0.024	0.026		
A1	0.00	0.03	0.05	0.000	0.001	0.002		
A3	0.15 Ref			0.006 Ref				
b	0.15	0.20	0.25	0.006	0.008	0.010		
b1	0.25	0.35	0.45	0.010	0.014	0.018		
D	2.90	3.00	3.10	0.114	0.118	0.122		
E	1.90	2.00	2.10	0.075	0.079	0.083		
е	0.60 BSC			0.	0.118 0.122			
e1	0.65 BSC			0.	026 BSC	0.008		
e2	0.95 BSC			0.037				
L	0.25	0.30	0.35	0.010	0.012	0.014		
L1	0.95	1.00	1.05	0.037	0.039	0.041		
Notes:								

- All dimensions are in millimeters
- 2. Dimensions include solder plating.
- 3. Dimensions are exclusive of mold flash & metal burr.

Tape & Reel Specification — µDFN-10 (3.0x2.0mm)



Package	μDFN-10 (3.0x2.0mm)		
Symbol	Millimeters		
A0	2.30 +/- 0.10		
В0	3.20 +/- 0.10		
Е	1.75 +/- 0.10		
F	3.50 +/- 0.05		
K0	1.0 +/- 0.10		
Р	4.00 +/- 0.10		
P0	4.00 +/- 0.10		
P2	2.00 +/- 0.10		
T	0.3 +/- 0.05		
W	8.00 +0.30/- 0.10		

Disclaimer Notice - Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at http://www.littelfuse.com/disclaimer-electronics

